



. One of the best Lm/W, Lm/\$ in Mid-Power LED (高光效、高性价比)

. Min-Power EMC packaging LED – 3020 Series (LED-3020 系列)

T34**011C-**AA (R,Y,G,B)



Table 1. Electro Optical Characteristics (光电特性), Ta = 25℃, RH60%, IF=150mA

Color	WD(nm)			VF(V)			φ(LM)		
	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max
RED	620	625	630		2.2	2.6		17	
YELLOW	585	590	595		2.2	2.6		17	
GREEN	520	525	530		3.1	3.6		37	
BLUE	460	465	470		3.1	3.4		10	

Table 2. Electro Optical Characteristics (光电特性), Ta = 25℃, RH60%

Item 参数	Symbol 符号	Colour	Value 数值			Unit 单位	Test Condition 测试条件
			Min 最小值	Typ 典型值	Max 最大值		
Reverse Current 反向电流	IR	RED	-	-	10	μA	VR=5V
		YELLOW					
		GREEN					
		BLUE					
View Angle 发光角度	2θ1/2	RED	-	120	-	°	IF=150mA
		YELLOW					
		GREEN					
		BLUE					
Electrostatic Discharge 抗静电	ESD	RED	2000V		-	°	HBM
		YELLOW					
		GREEN					
		BLUE					

- Tolerance of measurements of the Luminous Flux is ±7%. (LM 测试误差±7%)
- Tolerance VF :±0.1V (VF 测试误差±0.1V)



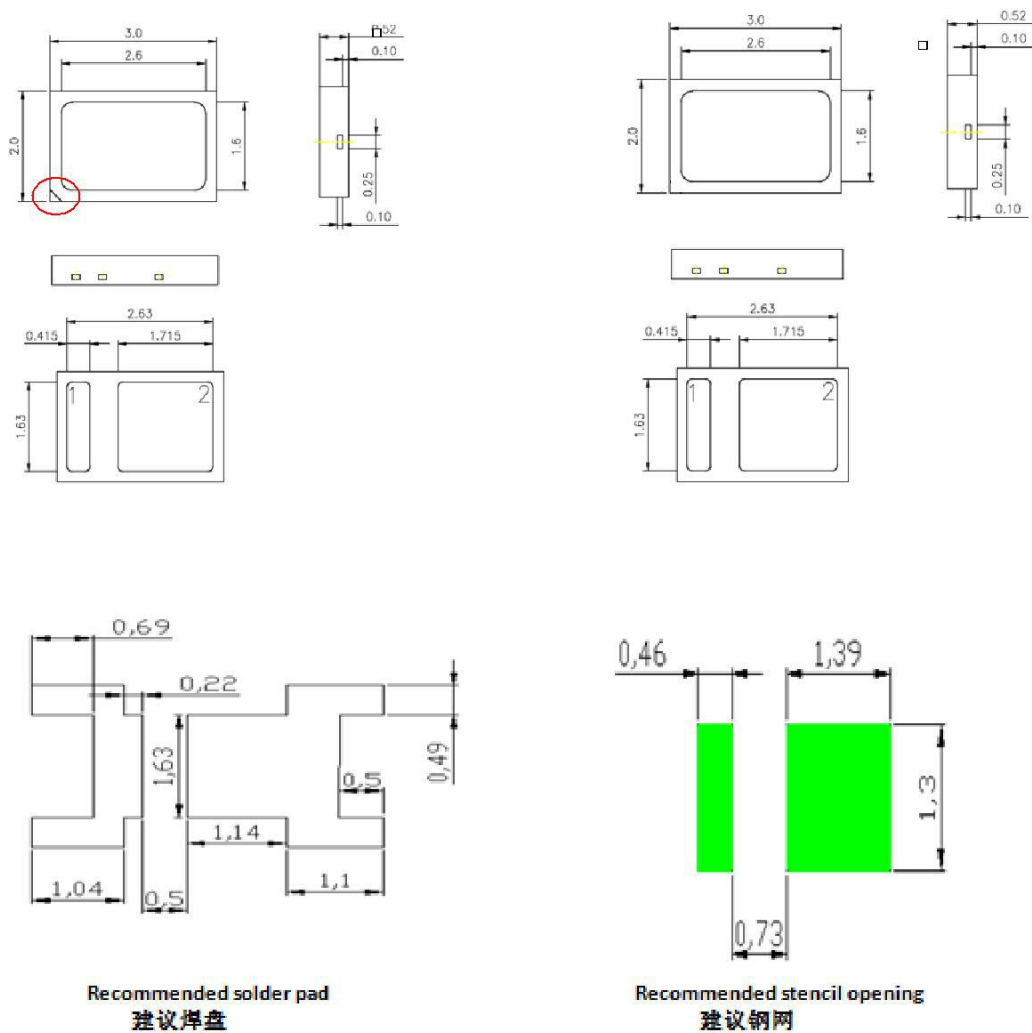
深圳市锐硕光电有限公司

Table 3. Absolute Maximum Ratings (最大额定参数), Ta = 25°C, RH60%

Item 参数名称	Symbol 符号	Absolute Maximum Ratings 最大额定参数		Unit 单位
Forward Current 正向电流	IF	200		mA
Pulse Forward Current 正向脉冲电流	IFP	300		mA
Power Dissipation 功率损耗	PD	BLUE	720	mW
		GREEN	720	
		AMBER	560	
		RED	560	
Reverse Voltage 反向电压	VR	5		V
Operating Temperature 操作温度	Topr	-40~+100		°C
Storage Temperature 储存温度	Tstg	-40~+100		°C
Junction Temperature 结温	Tj	125		°C
Soldering Temperature 回流温度	Tsld	230°C or 260°C for 10sec		

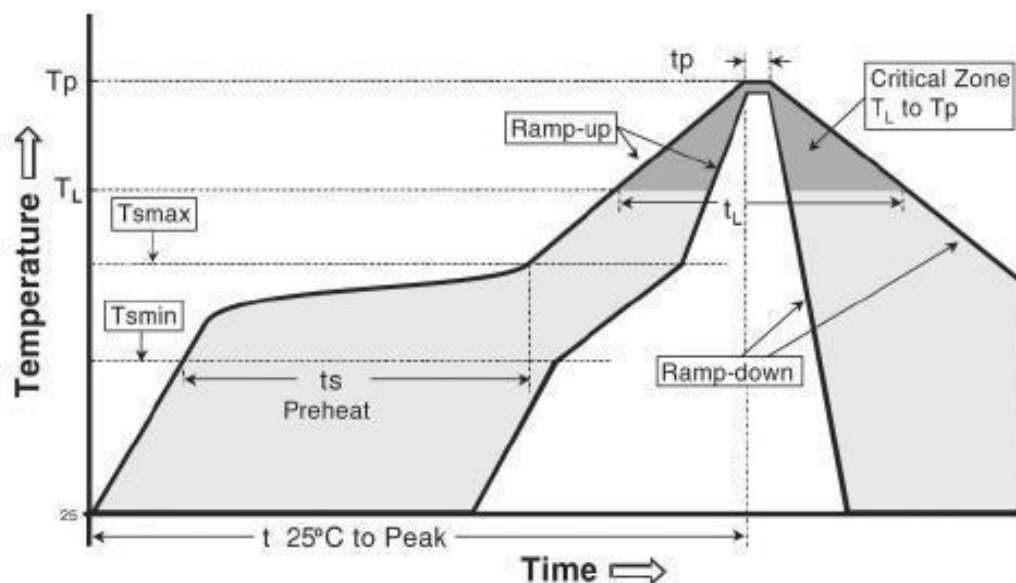
- IFP condition with Pulse: Width≤100μs Duty cycle≤1/10
- LED's properties might be different from suggested values like above and below tables if operation condition will be exceeded our parameter range. Care is to be taken that power dissipation does not exceed the absolute maximum rating of the product.
- 正向脉冲电流条件:脉冲宽度≤100μs, 占空比≤1/10
- 操作条件若超出最大额定参数, 可能会对 LED 造成不可预期伤害。

Mechanical Dimensions And Recommended Solder Pad (产品尺寸与焊盘设计)



- All dimensions are in millimeters (图中所有尺寸均以毫米为单位)
- Scale : 1:1 (比例: 1:1)
- Undefined tolerance is $\pm 0.2\text{mm}$ (尺寸公差: ± 0.2 毫米)
- This drawing without tolerances are for reference only (图纸仅供参考)

Reflow Soldering Characteristics (建议回流方式)



Reflow soldering	
Temperature Min (Tsmín)	150°C
Temperature Max (Tsmáx)	200°C
Time(ts)from (Tsmín to Tsmáx)	60-120 seconds.
Ramp-up rate (TL to Tp)	3°C/seconds max.
Liquidous temperature(TL)	217°C
Time(tL) maintained above TL	60-150 seconds
Peak package body temperature(Tp)	260°C max
Time (tp) within 5°C of the specified classification temperature(Tc).	30 seconds max
Ramp-down rate (Tp to TL)	6°C/second max
Time 25°C to peak temperature	8 min max

Caution (注意事项)

1. Reflow soldering is recommended not to be done more than two times. In the case of more than 24 hours passed soldering after first, LEDs will be damaged (回流焊建议不要超过两次) .
2. Repairs should not be done after the LEDs have been soldered. When repair is unavoidable, suitable tools must be used. (LED 焊接后不建议再重工, 当重工不可避免时,必须使用合适的工具) .
3. Die slug is to be soldered (不可虚焊) .
4. When soldering, do not put stress on the LEDs during heating (焊接加热过程中, 请勿施加压力于 LED 表面) .
5. After soldering, do not warp the circuit board (焊接后请勿弯曲电路板) .